



(2,16mm) .085"

DPAM, DPAF SERIES

HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:
DPAF, RDPAF

DPAF Mates with:
DPAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAM or www.samtec.com?DPAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au over 50µ" (1,27µm) Ni

Current Rating (2x3):

2.9A @ 30°C Temperature Rise

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10.4mΩ max

Working Voltage:

300 VAC

Mated Cycles:

100 Cycles

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes



Protocols Supported

- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- Infiniband
- XAUI
- MGT (Rocket I/O)

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

ALSO AVAILABLE

Tin-Lead Solder Charge.
Call Samtec.

Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

DPAM	PAIRS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION
	-04, -06 (-07.0 only) -08, -15, -23 (All lead styles)	Specify LEAD STYLE from chart	-S =30µ" (0,76µm) Gold on contact area, Tin on solder tail (-11 & -14 only) -H =30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail (-07 only)	-8 = Eight Pair Rows -3 = Three Pair Rows (-07 only)	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/.5% Cu Solder Crimp		-K = (20,00mm) 0.80" DIA Polyimide film Pick & Place Pad -TR = Tape & Reel -GP = Guide Post (-23 only & -07 only)

LEAD STYLE	A
-07.0	(6,66) .262
-11.0	(10,72) .422
-14.0	(13,66) .538

NO OF ROWS	B
-8	(24,59) .968
-3	(11,89) .468

Staggered pitch DPAM/DPAF	Rated @ 3dB Insertion Loss
10mm Stack Height	
Differential Pair Signaling	7.0 GHz / 14.0 Gbps
Performance data for other stack heights and complete test data available at www.samtec.com?DPAM , www.samtec.com?DPAF or contact sig@samtec.com	

DPAF	PAIRS PER ROW	03.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION
	-04, -06, -08, -15, -23		-H =30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail	-8 = Eight Pair Rows -3 = Three Pair Rows	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/.5% Cu Solder Crimp		-K = (20,00mm) 0.80" DIA Polyimide film Pick & Place Pad -TR = Tape & Reel

NO OF ROWS	A
-8	(23,32) .918
-3	(10,62) .418

SIZE	USABLE PAIRS PER ARRAY*
-08 x -8	48 Pairs
-15 x -8	104 Pairs
-23 x -8	168 Pairs
-08 x -3	18 Pairs
-15 x -3	39 Pairs
-23 x -3	63 Pairs

DPAM LEAD STYLE	DPAF MATED HEIGHT*
-07.0	10mm
-11.0	14mm
-14.0	17mm

Due to technical progress, all designs, specifications and components are subject to change without notice.

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